

# STL75N3LLZH5

### N-channel 30 V, 0.0055 Ω 19 A PowerFLAT™ (5x6) STripFET™ V Power MOSFET

Preliminary data

### **Features**

Туре	e V <sub>DSS</sub> R <sub>DS(on)</sub> max		I <sub>D</sub>
STL75N3LLZH5	30 V	<0.0061 Ω	19 A <sup>(1)</sup>

- 1. The value is rated according  $R_{thj-pcb}$
- R<sub>DS(on)</sub> \* Q<sub>g</sub> industry benchmark
- Extremely low on-resistance R<sub>DS(on)</sub>
- Very low switching gate charge
- High avalanche ruggedness
- Low gate drive power losses
- Built in G-S Zener diodes

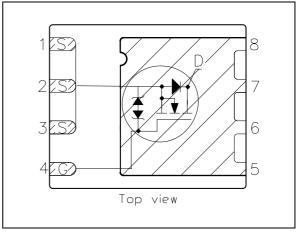
### Application

Switching applications

### Description

The STL75N3LLZH5 is an N-channel STripFET<sup>™</sup>V Power MOSFET which has been designed to achieve very low on-state resistance providing also one of the best-in-class figure of merit (FOM). Image: white of the second second

Figure 1. Internal schematic diagram



#### Table 1. Device summary

	Order code Marking		Package	Packaging	
Γ	STL75N3LLZH5	75N3LLZH5	PowerFLAT™ (5x6)	Tape and reel	

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## 1 Electrical ratings

Table 2.	Absolute	maximum	ratings
	/10001010	maximani	racingo

Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-source voltage (V <sub>GS</sub> = 0)	30	V
V <sub>GS</sub>	Gate-source voltage	± 18	V
I <sub>D</sub> <sup>(1)</sup>	Drain current (continuous) at T <sub>C</sub> = 25 °C	75	Α
I <sub>D</sub> <sup>(1)</sup>	Drain current (continuous) at T <sub>C</sub> = 100 °C	47	Α
I <sub>D</sub> <sup>(2)</sup>	Drain current (continuous) at T <sub>C</sub> = 25 °C	19	Α
I <sub>D</sub> <sup>(2)</sup>	Drain current (continuous) at T <sub>C</sub> =100°C	11.8	Α
I <sub>DM</sub> <sup>(3)</sup>	Drain current (pulsed)	76	Α
P <sub>TOT</sub> <sup>(1)</sup>	Total dissipation at $T_{C} = 25^{\circ}C$	60	W
P <sub>TOT</sub> <sup>(2)</sup>	Total dissipation at $T_{C} = 25^{\circ}C$	4	W
	Derating factor	0.03	W/°C
T <sub>J</sub> T <sub>stg</sub>	Operating junction temperature Storage temperature	-55 to 150	°C

1. The value is rated according  ${\sf R}_{thj\text{-}c}$  .

2. The value is rated according  $\mathsf{R}_{thj\text{-pcb.}}$ 

3. Pulse width limited by safe operating area.

Table 3. Thermal resistance
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Symbol	Parameter	Value	Unit
R <sub>thj-case</sub>	Thermal resistance junction-case (Drain) (steady state)	2.08	°C/W
R <sub>thj-pcb</sub> <sup>(1)</sup>	Thermal resistance junction-ambient	31.3	°C/W

1. When mounted on FR-4 board of 1inch<sup>2</sup>, 2oz Cu, t < 10 sec



## 2 Electrical characteristics

(T<sub>CASE</sub> = 25 °C unless otherwise specified).

	On/on states					
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source breakdown voltage	$I_{D} = 250 \ \mu A, \ V_{GS} = 0$	30			V
I <sub>DSS</sub>	Zero gate voltage drain current (V <sub>GS</sub> = 0)	V <sub>DS</sub> = max rating, V <sub>DS</sub> = max rating @125 °C			1 10	μΑ μΑ
I <sub>GSS</sub>	Gate body leakage current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 18 V			±10	μA
V <sub>GS(th)</sub>	Gate threshold voltage	$V_{DS}$ = $V_{GS}$ , $I_D$ = 250 $\mu$ A	1			V
R <sub>DS(on)</sub>	Static drain-source on resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 9.5 A V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 9.5 A		0.0055 0.0066	0.0061 0.0078	Ω Ω

#### Table 4. On/off states

#### Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input capacitance Output capacitance Reverse transfer capacitance	V <sub>DS</sub> =25 V, f=1 MHz, V <sub>GS</sub> =0	-	1510 287 40	-	pF pF pF
Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub>	Total gate charge Gate-source charge Gate-drain charge	V <sub>DD</sub> =15 V, I <sub>D</sub> = 19 A V <sub>GS</sub> =4.5 V <i>Figure 3</i>	-	11.8 4 6	-	nC nC nC

#### Table 6.Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub> t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub>	Turn-on delay time Rise time Turn-off delay time Fall time	$V_{DD}$ =15 V, $I_D$ = 9.5 A, R <sub>G</sub> =4.7 $\Omega$ , $V_{GS}$ =10 V <i>Figure 2</i>	-	9.2 11 55 20	-	ns ns ns ns

Symbol	Parameter	Test conditions	Min	Тур.	Max	Unit
I <sub>SD</sub>	Source-drain current		-		19	А
I <sub>SDM</sub> <sup>(1)</sup>	Source-drain current (pulsed)		-		76	А
V <sub>SD</sub> <sup>(2)</sup>	Forward on voltage	I <sub>SD</sub> = 19 A, V <sub>GS</sub> =0	-		1.1	V
t <sub>rr</sub>	Reverse recovery time	I <sub>SD</sub> = 19 A,		24		ns
Q <sub>rr</sub>	Reverse recovery charge	di/dt = 100 A/µs,	-	17		nC
I <sub>RRM</sub>	Reverse recovery current	V <sub>DD</sub> =25 V, Tj=150 °C		1.4		А

 Table 7.
 Source drain diode

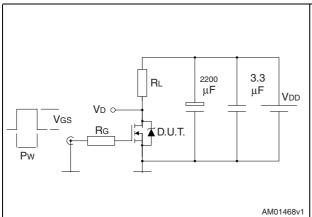
1. Pulse width limited by safe operating area.

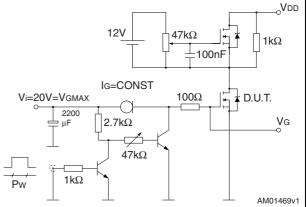
2. Pulsed: pulse duration= 300  $\mu$ s, duty cycle 1.5%.



### 3 Test circuits

Figure 2. Switching times test circuit for resistive load





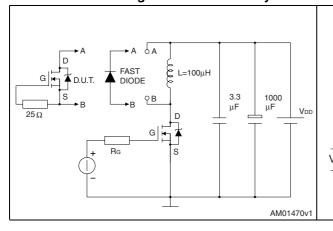
Gate charge test circuit

Figure 3.

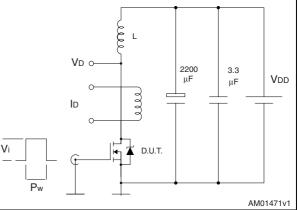
Figure 5.

circuit

Figure 4. Test circuit for inductive load switching and diode recovery times

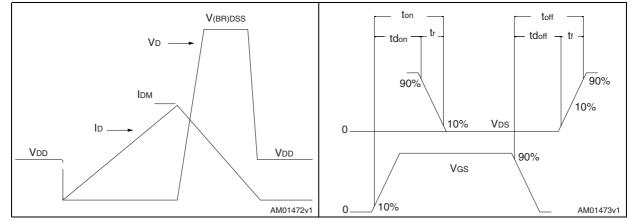






**Unclamped inductive load test** 







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### 4 Package mechanical data

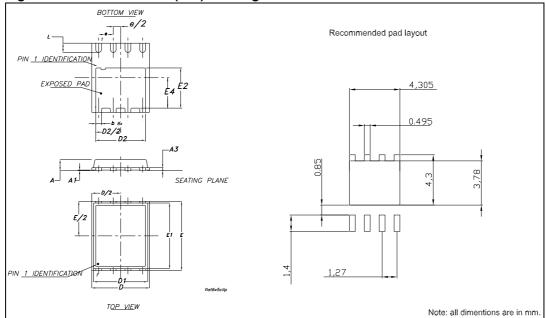
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.



		(0.00)	indifiour data	dutu			
Dim.		mm.			inch.		
	Min.	Тур.	Max.	Min.	Тур.	Max.	
А	0.80	0.83	0.93	0.031	0.32	0.036	
A1		0.02	0.05		0.0007	0.0019	
A3		0.20			0.007		
b	0.35	0.40	0.47	0.013	0.015	0.018	
D		5.00			0.196		
D1		4.75			0.187		
D2	4.15	4.20	4.25	0.163	0.165	0.167	
E		6.00			0.236		
E1		5.75			0.226		
E2	3.43	3.48	3.53	0.135	0.137	0.139	
E4	2.58	2.63	2.68		0.103	0.105	
е		1.27			0.050		
L	0.70	0.80	0.90	0.027	0.031	0.035	

 Table 8.
 Power FLAT™ (5x6) mechanical data





## 5 Revision history

### Table 9.Document revision history

Date	Revision	Changes
22-Jun-2010	1	First release.
08-Jul-2010	2	Modified V <sub>GS</sub> in <i>Table 2: Absolute maximum ratings</i> and <i>Table 4: On/off states</i> .



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